

Electronic Patent Application Fee Transmittal

Application Number:	10790723			
Filing Date:	03-Mar-2004			
Title of Invention:	Wafer level package for micro device and manufacturing method thereof			
First Named Inventor:	Joo Ho Lee			
Filer:	Benjamin J. Hauptman/Ayesha Wilson			
Attorney Docket Number:	2336-247			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	1201	1	200	200
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				200